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# **MICROELECTROMECHANICAL SYSTEM DEVICE PACKAGE AND PACKAGING METHOD**

## Abstract of Disclosure

A method for packaging a microelectromechanical system (MEMS) device comprises: using a partially-cured adhesive to attach a release sheet to a MEMS package flexible layer; providing a cavity extending through the release sheet and at least partially through the MEMS package flexible layer; removing the release sheet; and attaching the MEMS device to the MEMS package flexible layer with a MEMS structure of the MEMS device being positioned within the cavity.

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## Figures